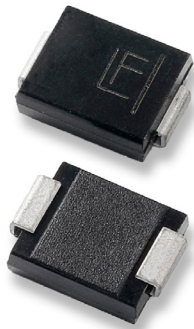


# 3.0SMC Series

## Surface Mount



Uni-directional



### Additional Information



Resources



Accessories



Samples

### Maximum Ratings and Thermal Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Power Dissipation on Infinite Heat Sink at $T_L=50^\circ\text{C}$	$P_D$	6.5	W
Peak Forward Surge Current, 8.3ms Single Half Sine Wave (Note 1)	$I_{FSM}$	300	A
Maximum Instantaneous Forward Voltage at 100A for Unidirectional Only	$V_F$	3.5	V
Operating Temperature Range	$T_J$	-65 to 150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-65 to 175	$^\circ\text{C}$
Typical Thermal Resistance Junction to Lead	$R_{\theta JL}$	15	$^\circ\text{C}/\text{W}$
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	75	$^\circ\text{C}/\text{W}$

#### Notes:

1. Measured on 8.3ms single half sine wave or equivalent square wave for unidirectional device only, duty cycle = 4 per minute maximum.

### Description

The 3.0SMC series is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events.

### Features & Benefits

- For surface mounted applications in order to optimize board space
- Low profile package
- Typical failure mode is short from over-specified voltage or current
- Whisker test is conducted based on JEDEC JESD201A per its table 4a and 4c
- IEC-61000-4-2 ESD 30kV(Air), 30kV (Contact)
- $I_{pp}$  is specified @ 8/20 $\mu\text{s}$  surge waveform
- Built-in strain relief
- $V_{BR} @ T_J = V_{BR} @ 25^\circ\text{C} \times (1 + \alpha T \times (T_J - 25))$  ( $\alpha$ : Temperature Coefficient, typical value is 0.1%)
- Glass passivated chip junction
- Fast response time: typically less than 1.0ps from 0V to BV min
- Excellent clamping capability
- Low incremental surge resistance
- High temperature to reflow soldering guaranteed: 260 $^\circ\text{C}/40\text{sec}$
- Meet MSL level1, per J-STD-020, LF maximum peak of 260 $^\circ\text{C}$
- Matte tin lead-free plated
- Halogen free and RoHS compliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)

### Applications

TVS devices are ideal for the protection of I/O Interfaces,  $V_{CC}$  bus and other vulnerable circuits used in Telecom, Computer, Industrial and Consumer electronic applications.

### Functional Diagram



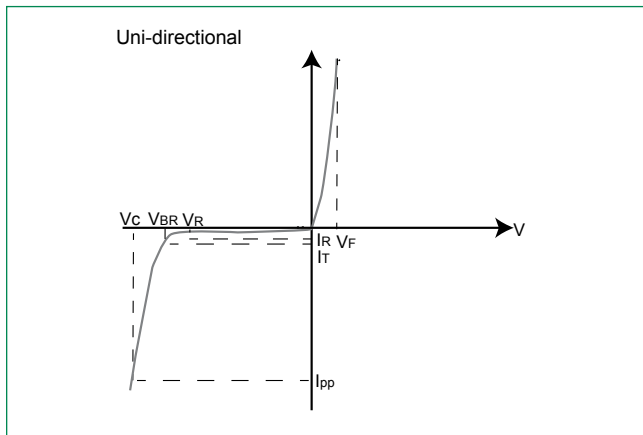
# 3.0SMC Series

## Surface Mount

### Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Part Number (Uni)	Marking	Reverse Stand off Voltage $V_R$ (Volts)	Breakdown Voltage $V_{BR}$ (Volts) @ $I_T$		Test Current $I_T$ (mA)	Maximum Clamping Voltage $V_C$ @ $8/20\mu\text{S}$ $I_{pp}$ (V)	Maximum Peak Pulse Current $I_{pp}$ @ $8/20\mu\text{S}$ (A)	Maximum Reverse Leakage $I_R$ @ $V_R$ ( $\mu\text{A}$ )
			MIN	MAX				
3.0SMC20A	YLA	20.0	22.20	24.50	1	42	570	1
3.0SMC24A	YLC	24.0	26.70	29.50	1	51	520	1
3.0SMC28A	YLE	28.0	31.10	34.40	1	59	470	1
3.0SMC30A	YLF	30.0	33.30	36.80	1	62	420	1
3.0SMC33A	YLG	33.0	36.70	40.60	1	70	365	1

### I-V Curve Characteristics



$P_{ppm}$  Peak Pulse Power Dissipation – Max power dissipation  
 $V_R$  Stand-off Voltage – Maximum voltage that can be applied to the TVS without operation  
 $V_{BR}$  Breakdown Voltage – Maximum voltage that flows through the TVS at a specified test current ( $I_T$ )  
 $V_C$  Clamping Voltage – Peak voltage measured across the TVS at a specified  $I_{ppm}$  (peak impulse current)  
 $I_R$  Reverse Leakage Current – Current measured at  $V_R$   
 $V_F$  Forward Voltage Drop for Uni-directional

### Ratings and Characteristic Curves ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Figure 1 - TVS Transients Clamping Waveform

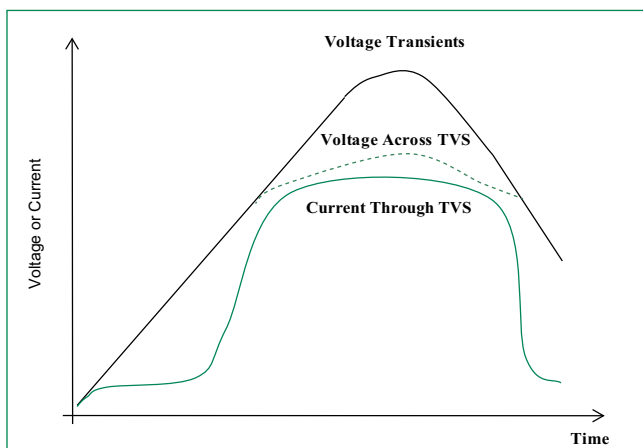
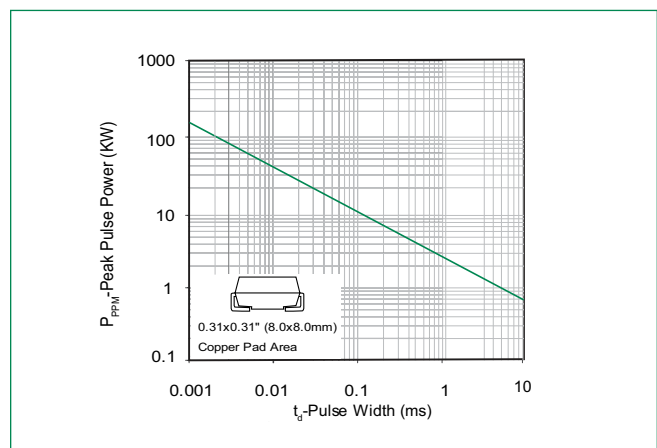


Figure 2 - Peak Pulse Power Rating

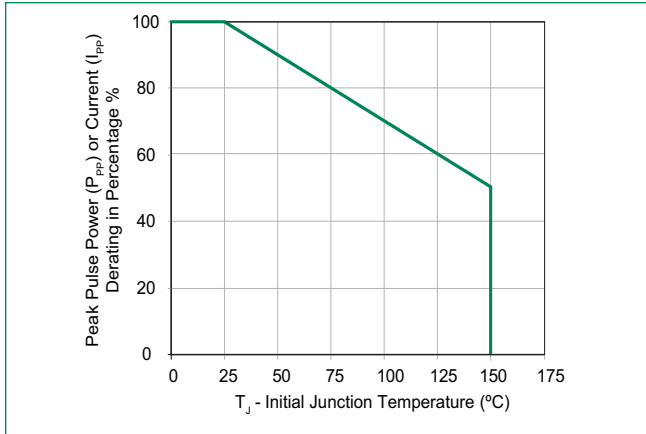


# 3.0SMC Series

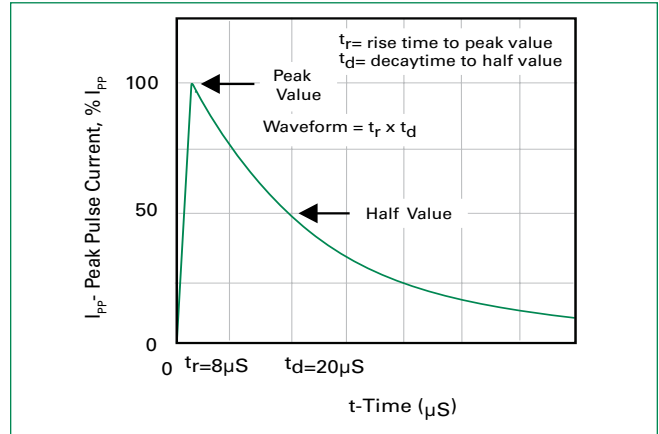
## Surface Mount

### Ratings and Characteristic Curves ( $T_A=25^{\circ}\text{C}$ unless otherwise noted) (Continued)

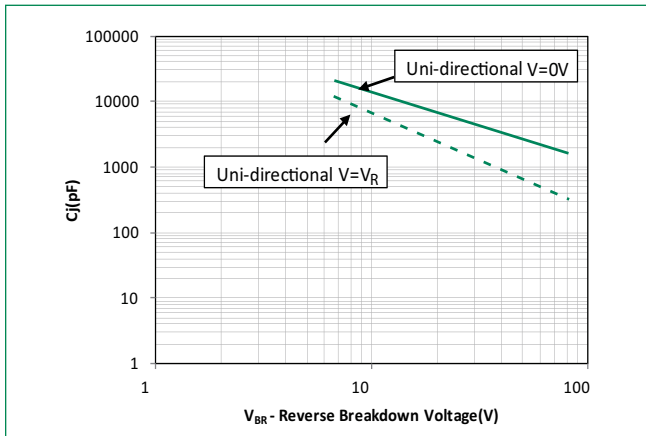
**Figure 3 - Peak Pulse Power Derating Curve**



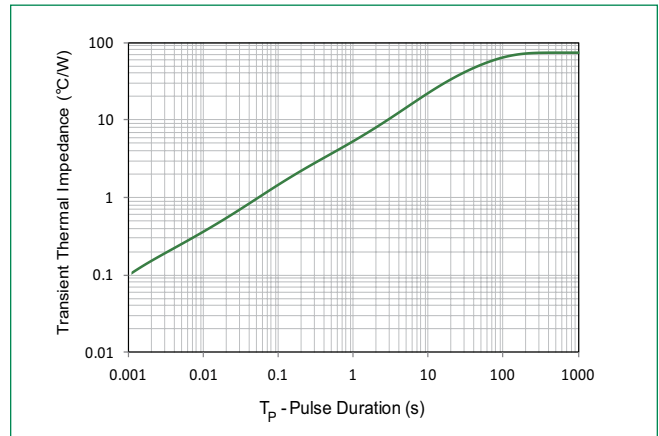
**Figure 4 - Pulse Waveform**



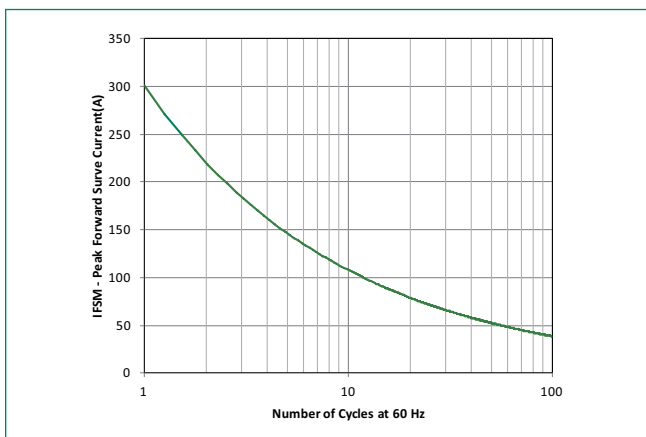
**Figure 5 - Typical Junction Capacitance**



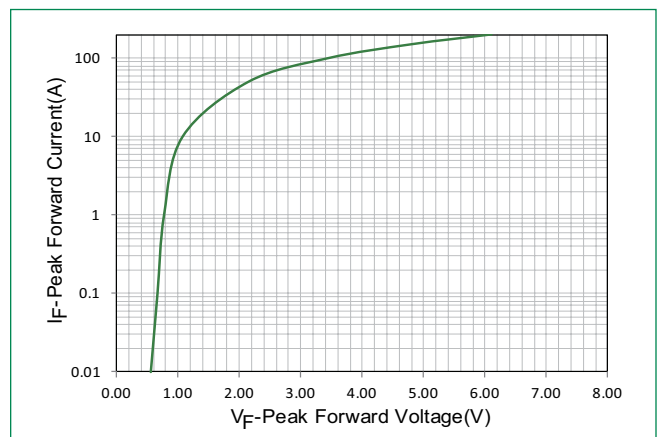
**Figure 6 - Typical Transient Thermal Impedance**



**Figure 7 - Maximum Non-Repetitive Peak Forward Surge Current Uni-Directional only**



**Figure 8 - Peak Forward Voltage Drop vs Peak Forward Current (Typical Values)**

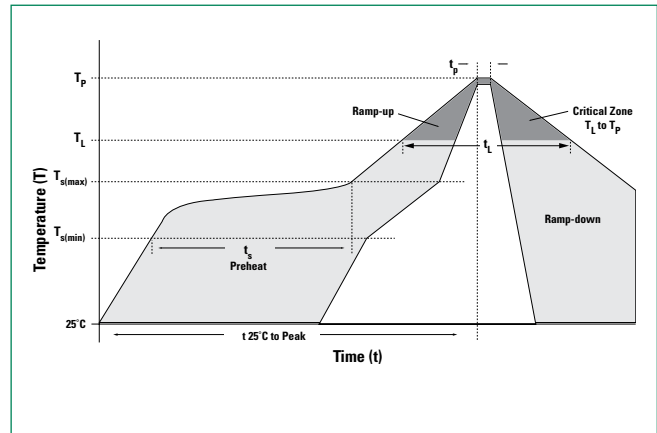


# 3.0SMC Series

## Surface Mount

### Soldering Parameters

<b>Reflow Condition</b>		Lead-free assembly
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 180 secs
<b>Average ramp up rate (Liquidus Temp (<math>T_A</math>) to peak)</b>		3°C/second max
<b><math>T_{s(max)}</math> to <math>T_A</math> - Ramp-up Rate</b>		3°C/second max
<b>Reflow</b>	- Temperature ( $T_A$ ) (Liquidus)	217°C
	- Time (min to max) ( $t_s$ )	60 – 150 seconds
<b>Peak Temperature (<math>T_p</math>)</b>		260 <sup>+0/-5</sup> °C
<b>Time within 5°C of actual peak Temperature (<math>t_p</math>)</b>		20 – 40 seconds
<b>Ramp-down Rate</b>		6°C/second max
<b>Time 25°C to peak Temperature (<math>T_p</math>)</b>		8 minutes Max.
<b>Do not exceed</b>		260°C



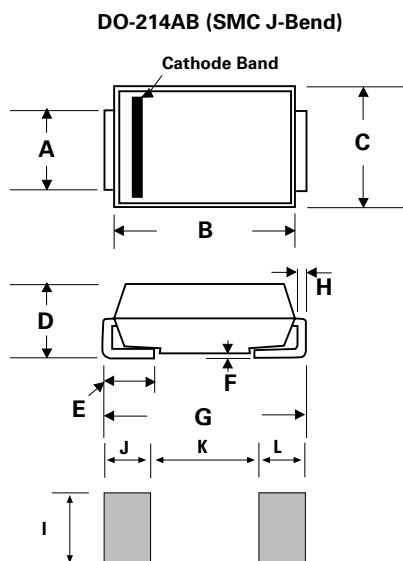
### Physical Specifications

<b>Weight</b>	0.007 ounce, 0.21 grams
<b>Case</b>	JEDEC DO214AB. Molded plastic body over glass passivated junction
<b>Polarity</b>	Color band denotes positive end (cathode) except Bidirectional.
<b>Terminal</b>	Matte Tin-plated leads, Solderable per JESD22-B102

### Environmental Specifications

<b>High Temp. Storage</b>	JESD22-A103
<b>HTRB</b>	JESD22-A108
<b>Temperature Cycling</b>	JESD22-A104
<b>MSL</b>	JEDEC-J-STD-020, Level 1
<b>H3TRB</b>	JESD22-A101
<b>RSH</b>	JESD22-A111

### Dimensions

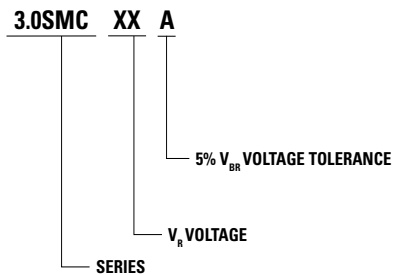


Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.114	0.126	2.900	3.200
B	0.260	0.280	6.600	7.110
C	0.220	0.245	5.590	6.220
D	0.079	0.103	2.060	2.620
E	0.030	0.060	0.760	1.520
F	-	0.008	-	0.203
G	0.305	0.320	7.750	8.130
H	0.006	0.012	0.152	0.305
I	0.129	-	3.300	-
J	0.094	-	2.400	-
K	-	0.165	-	4.200
L	0.094	-	2.400	-

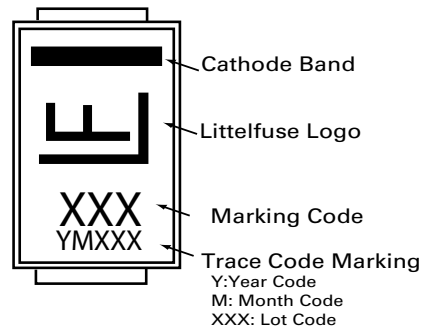
# 3.0SMC Series

## Surface Mount

### Part Numbering System



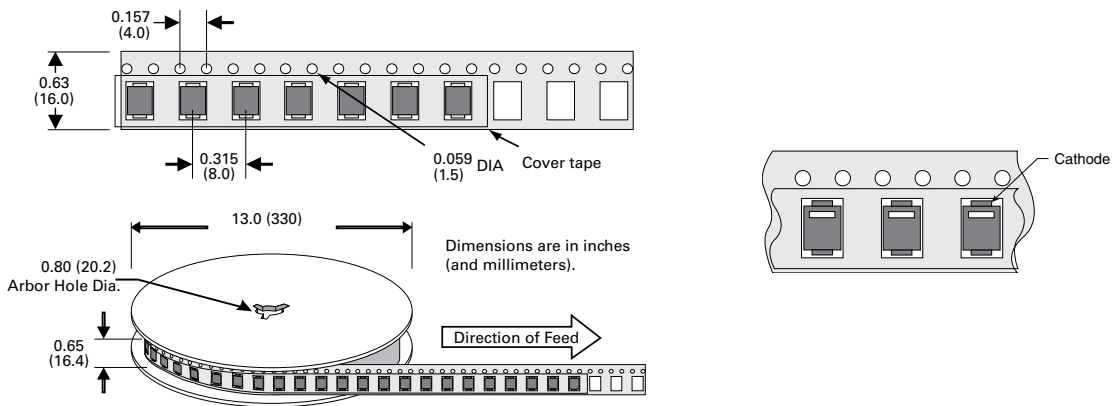
### Part Marking System



### Packaging Options

Part number	Component Package	Quantity	Packaging Option	Packaging Specification
3.0SMCxxX	DO-214AB	3000	Tape & Reel - 16mm tape/13" reel	EIA STD RS-481

### Tape and Reel Specification



**Disclaimer Notice** - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at [www.littelfuse.com/disclaimer-electronics](http://www.littelfuse.com/disclaimer-electronics).